

**Notice of References Cited**

Application/Control No.

10/820,312

Applicant(s)/Patent Under  
Reexamination  
OKA ET AL.

Examiner

Patricia A. George

Art Unit

1765

Page 1 of 3

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Miller et al. (An Electromagnetic MEMS 2 x 2 Fiber Optic bypass Switch; Cal Tech & Physics Optics Corp; page 2, column 1; 1997).□□
*	V	Kim et al. (Characterization of the Post Dry-Etch Cleaning of Silicon for Ti-Self-Aligned Silicide Technology; J. Electrochem. Soc., Volume 146, Issue 4, pp. 1549-1556; April 1999)□□Raynaud et al. (Cleaning of silicon surf
*	W	Raynaud et al.; Cleaning of silicon surfaces by argon microwave multipolar plasmas excited by distributed electron cyclotron resonance; Journal of Vacuum Science and Technology B; Microelectronics and Nanometer Structures; May 1993; vol.11, issue 3, pp 699-708
*	X	Holke; Ultra deep anisotropic etch of 110 silicon; Journal of Micromechanics and Microengineering; 9, 1999; 51-57

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

<b>Notice of References Cited</b>	Application/Control No. 10/820,312	Applicant(s)/Patent Under Reexamination OKA ET AL.	
	Examiner Patricia A. George	Art Unit 1765	Page 2 of 3

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,682,871	01-2004	Zhang, Nan	430/311
*	B	US-6,271,955	08-2001	Atobe et al.	359/291
*	C	US-6,108,121	08-2000	Mansell et al.	359/291
*	D	US-6,921,081	07-2005	Wobben, Aloys	277/549
*	E	US-2002/0086456	07-2002	Cunningham et al.	438/57
*	F	US-2002/0102059	08-2002	Cho et al.	385/49
*	G	US-6,639,572	10-2003	Little et al.	345/55
*	H	US-6,852,362	02-2005	Nakayama et al.	427/248.1
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	MSDS for TMAH <a href="http://nantech.wisc.edu">http://nantech.wisc.edu</a>
*	V	powell et al.; Anisotropic Etching of 110 and 111 planes in 100 silicon; Journal of Micromechanics and Microengineering; 11, 2001, 217-220
*	W	Wikipedia; <a href="http://en.wikipedia.org/wiki/Thin-film_deposition">http://en.wikipedia.org/wiki/Thin-film_deposition</a>
*	X	Society of Vacuum Coaters; 44th anual technical conference proceedings; 2001; society of vacuum coaters.

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

<b>Notice of References Cited</b>	Application/Control No. 10/820,312	Applicant(s)/Patent Under Reexamination OKA ET AL.	
	Examiner Patricia A. George	Art Unit 1765	Page 3 of 3

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Helin et al.; Self-Aligned Micromachining process for large Scale, Free-Space optical Cross-Connects; 1000 IEEE
	V	IUC; 2002; The Diagrams; www.iucr.org/iucr-top/comm/cteach/pamphlets/12/node4.html
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.